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Claim 14 recites a first bond pad, a second set of bond pads having one or more bond pads, and a third bond pad, wherein the second set of bond pads is immediately adjacent to the first and third bond pads. In addition, claim 14 recites a conductive trace coupling the first bond pad to the third bond pad. FIG. 6 illustrates a specific embodiment of claim 14 whereby a first bond pad 172 is conductively coupled to a third bond pad 174, and a second set of bond pads, comprising a single bond pad adjacent to the first and third bond pads, is represented by bond pad 173.

The Office indicated in the Final Rejection dated November 19, 2002, that U.S. Patent Kameda discloses these claimed limitations. However, examination of the cited reference, and specifically FIGs. 2 and 3 of Kameda, indicates that Kameda does not disclose or suggest the claimed limitations.

Referring to FIG. 2, three bond pads, bond pad 4, bond pad 11A, and bond pad 11B, are illustrated. One conductive trace couples bond pad 11B to a first buffer 2 that in turn provides a signal to a trace 8. A second conductive trace couples bond pad 11A to a second buffer 2 that in turn provides a signal to another trace 8. A third conductive trace 6, that is not coupled to either of the traces to the bond pads 11A or 11B is coupled to a third bond pad 4. The fact that the traces to bond pads 4, 11A and 11B are separate traces is better illustrated in the application by looking at the cross-section 3 (FIG. 2) which highlights the locations of each of the traces to the three bond pads.

The cross-section 3 is illustrated in FIG. 3 whereby it can be seen that the first conductive trace coupling 11B to the buffer 2 is at a first layer 21, a second conductive trace coupling bond pad 11A to the buffer 2 is at a second layer 22, and a third conductive trace coupling the power supply bond pad 4 to a power bus is at yet a third layer 23. Therefore, the recited element of claim 14 coupling the first bond pad to the third bond pad is not disclosed by FIGs. 2 or 3 or by Kameda.

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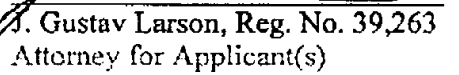
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For this reason, withdrawal of the rejection under §102 is respectfully request, and allowance of claim 14 and its dependent claims is respectfully solicited.

In conclusion, Applicant has overcome all of the Office's rejections, and early notice of allowance to this effect is earnestly solicited. If, for any reason, the Office is unable to allow the Application on the next Office Action, and believes a telephone interview would be helpful, the Examiner is respectfully requested to contact the undersigned attorney.

Respectfully submitted,

CERTIFICATE OF FACSIMILE	
I hereby certify that this correspondence is being facsimile transmitted to the United States Postal Service on <u>1-21-03</u> .	
Terri Alloway Typed or Printed Name	<u>Terri Alloway</u> Signature


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